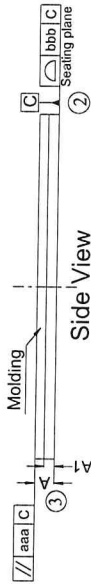
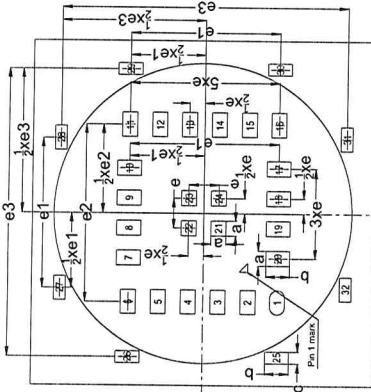


Top View  
阴影部分为可切割区域



Side View



Bottom View

DIMENSIONAL REFERENCES Units:mm

DIMENSIONAL REQMTS		Tolerance of Form & Position	
SYMBOL	MIN NOM MAX	aaa	bbb
A	0.61 0.65 0.69	0.10	0.10
A1	0.32 0.35 0.38		
D	11.40 11.50 11.60		
E	11.40 11.50 11.60		
a	0.45 0.50 0.55		
b	0.75 0.80 0.85		
c	0.35 0.40 0.45		
e	1.00 BCS		
e1	5.00 BCS		
e2	5.90 BCS		
e3	9.60 BCS		

Note:

- All dimensions are in mm.
- Datum 'C' is the mounting surface, with which the package is in contact
- Dimension 'A' include the package warpage.

PIN	Value	PIN	Value	PIN	Value
1	NC	12	PD_POWER_N	23	GND
2	GND	13	FINGER	24	GND
3	VCC	14	CS	25	NC
4	I_RING	15	INT	26	NC
5	COUT	16	TX_RING	27	NC
6	NC	17	KEY_PIN	28	NC
7	SDI	18	LDO_RING	29	NC
8	SDO	19	VCAL	30	NC
9	ESD_GND	20	VTX	31	NC
10	SCL	21	GND	32	NC
11	TX_POWER	22	GND		



池州华宇电子科技股份有限公司  
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

图号 Drawing No.

HY-POD-LGA0021

Title

产品外形图  
PACKAGE OUTLINE DIMENSIONS  
LGA20L (11.5X11.5X0.65~P1.00)

幅图 size

A4

页数 page

1

单位 unit

mm

比例 scale

1:1

视图 view



制图: Draw

2024.08.14

研发部: R&D Check

产品工程部: PE Check

生产部: Product Department

核准: Approved

2024.8.14